

IN THE CLAIMS

Please cancel claim 18 without prejudice or disclaimer as to its subject matter by this amendment, amend claims 3, 4, 9, 10 and 17 by this amendment and newly added claim 23 by this amendment as follows:

1 1. (Previously Presented) A filter, comprising:

2 a substrate;

3 a conductive material pattern arranged on the substrate, the conductive material pattern
4 comprising a conductive material, the conductive material having a pattern;

5 a negative photoresist pattern, patterned on the substrate on portions not covered by the
6 conductive material pattern to complement the conductive material pattern, the negative
7 photoresist pattern comprising a negative photoresist material that comprises a pigment and a dye
8 that cuts off light of a specific wavelength range, the negative photoresist material further
9 comprising a material that prevents external light from being reflected; and

10 a plated mesh arranged on a conductive material pattern.

1 2. (Previously Presented) The filter of claim 1, the negative photoresist material
2 comprising a material selected from the group consisting of a transparent acryl group and a
3 phenol group.

1 3. (Currently Amended) The filter of claim 1, the dye comprising an organic compound

2 selected from the group consisting of an imonium group and a phthalocyanin group, the pigment
3 comprising an organic compound of the imonium group, the dye blocking only near infrared rays.

1 4. (Currently Amended) The filter of claim 1, the dye comprising an organic compound
2 selected from the group consisting of an imonium group and a phthalocyanin group, the pigment
3 comprising an organic compound of the imonium group, the dye blocking only light having a
4 wavelength near 590 nm.

1 5. (Previously Presented) The filter of claim 1, a combined thickness of the conductive
2 material pattern and the plated mesh arranged thereon being in a range of 1 to 50 μm .

1 6. (Previously Presented) The filter of claim 1, wherein said material that prevents
2 external light from being reflected being selected from the group consisting of a metal powder
3 and an inorganic metal oxide.

1 7. (Previously Presented) The filter of claim 1, the filter being formed by a process
2 comprising:

3 coating an entire surface of the substrate with a layer of the conductive material;

4 forming a predetermined positive photoresist pattern on the conductive material by
5 applying the photoresist, exposing the photoresist and developing the exposed photoresist;

6 etching exposed portions of the conductive material;

7 removing said patterned positive photoresist leaving the conductive material pattern on
8 the substrate;

9 coating said entire surface of the substrate having the conductive material pattern with the
10 negative photoresist material;

11 exposing the negative photoresist material by illuminating said substrate from a side
12 opposite from said surface containing said conductive material pattern and the negative
13 photoresist material;

14 developing the exposed negative photoresist material to form the negative photoresist
15 pattern exposing said conductive material pattern; and

16 forming the plated mesh on the exposed conductive material pattern by electrical plating.

1 8. (Previously Presented) The filter of claim 7, wherein the negative photoresist material
2 comprises a material selected from the group consisting of a transparent acryl group and a phenol
3 group.

1 9. (Currently Amended) The filter of claim 7, the dye comprises an organic compound of
2 an imonium group, and the pigment comprises an organic compound of the imonium group, the
3 dye filtering out only near infrared rays.

1 10. (Currently Amended) The filter of claim 7, wherein the dye is an organic compound
2 of an imonium group or a phthalocyanin group, and the pigment is an organic compound of the

3 imonium group, the dye blocking only light having a wavelength of about 590 nm.

1 11. (Previously Presented) The filter of claim 1, the filter being formed by a process
2 comprising:

3 forming the conductive material pattern on a first side of the substrate;

4 applying a layer of the negative photoresist material on said first side of said substrate;

5 exposing a pattern in said layer of negative photoresist material by illuminating a side of
6 said substrate opposite said first side;

7 developing said layer of negative photoresist material resulting in said negative
8 photoresist pattern; and

9 increasing a thickness of said conductive material pattern on said first side of said
10 substrate by electroplating.

1 Claim 12 (Canceled)

1 13. (Previously Presented) The filter of claim 11, said conductive material pattern being
2 formed by a process comprising:

3 forming a blanket layer of the conductive material;

4 applying, patterning, and developing a positive photoresist layer on the blanket layer of
5 conductive material;

6 then etching the blanket layer of conductive material with patterned photoresist thereon;

7 and then

8 removing the patterned positive photoresist.

1 14. (Previously Presented) The filter of claim 13, said blanket layer of conductive
2 material being formed by sputtering.

1 15. (Previously Presented) The filter of claim 11, the process further comprising adding
2 additives to said negative photoresist prior to said applying step, the additives being adapted to
3 filter out near infrared wavelengths.

1 16. (Previously Presented) The filter of claim 11, said conductive material pattern
2 adapted to serve as a mask in said exposing step.

1 17. (Currently Amended) A filter, comprising:
2 a substrate that is transparent to light;
3 a conductive mesh pattern arranged on one side of the substrate; and
4 a non conductive material arranged on said one side of said substrate at locations absent
5 said conductive mesh, said conductive mesh pattern and said non-conductive material having
6 equal depths between 1 and 50 microns.

1 18. (Canceled)

1 19. (Previously Presented) The filter of claim 17, said non conductive material
2 comprising negative photoresist comprising additives.

1 20. (Previously Presented) The filter of claim 17, said conductive mesh pattern being
2 electrically grounded.

1 21. (Previously Presented) The filter of claim 17, said conductive mesh pattern having a
2 grid pattern.

1 22. (Previously Presented) The filter of claim 19, said additives comprising a dye.

1 23. (New) A filter, comprising:
2 a substrate that is transparent to light;
3 a conductive mesh pattern arranged on one side of the substrate; and
4 a non conductive material arranged on said one side of said substrate on a same level as
5 said conductive mesh pattern, said non conductive material complementing the conductive mesh
6 pattern and being adapted to filter out light only of specific wavelengths, said conductive mesh
7 pattern and said non-conductive material having equal depths of between 1 and 50 microns.